

**AMENDMENTS TO THE CLAIMS**

1. (Currently amended) A method of fabricating ~~a molecular electronic~~ an organic light emitting diode device, the method comprising:

fabricating a substrate having a plurality of banks defining wells for the deposition of molecular material; and

depositing into said wells a composition comprising a molecular electronic material dissolved in a solvent, using a droplet deposition technique, to fabricate said device;

wherein a said bank has a face, defining an edge of said well, at an angle to a base of the well of greater than a contact angle of said composition with said bank face; and

wherein a height of a said bank above a said base of a said well is less than  $2\mu\text{m}$ ; and

wherein the step of depositing the composition comprising the molecular electronic material comprises depositing an organic hole transporting layer and depositing an organic electroluminescent layer thereover, both the organic hole transport layer and the organic electroluminescent layer being deposited by the droplet deposition technique.

2. (Original) A method as claimed in claim 1 wherein a height of a said bank above a said base of a said well is less than  $1\mu\text{m}$ .

3. (Currently amended) A method as claimed in claim 1 ~~of fabricating a molecular electronic device, the method comprising:~~

~~fabricating a substrate having a plurality of banks defining wells for the deposition of molecular material; and~~

~~depositing into said wells a composition comprising a molecular electronic material dissolved in a solvent, using a droplet deposition technique, to fabricate said device;~~

~~wherein a said bank has a face, defining an edge of said well, at an angle to a base of the well of greater than a contact angle of said composition with said bank face; and~~

wherein said method further comprises determining a number of droplets to deposit into a said well taking account of a tendency for said dissolved material to be drawn along a said bank face by surface wetting.

4. (Original) A method as claimed in claim 3 further comprising depositing at least one droplet of dissolved molecular electronic material such that on deposition it spreads to touch a said bank face.

5. (Canceled)

6. (Previously presented) A method as claimed in claim 1 further comprising lithographically forming said banks from a photoresist.

7. (Canceled)

8. (Currently amended) A method as claimed in claim ~~[[7]]~~6 wherein said photoresist comprises a single layer of negative photoresist.

9. (Currently amended) A method as claimed claim 1 wherein ~~[[a]]~~ said bank face angle is at least 40 degrees.

10. (Currently amended) A method as claimed in claim 1 wherein ~~[[a]]~~ said bank face is undercut.

11. (Previously presented) A method as claimed in claim 1 wherein said depositing step comprises depositing droplets which, on deposition, incompletely fill a said well in a lateral plane of said substrate.

12. (Withdrawn) A substrate for a molecular electronic device, the substrate having a plurality of banks defining wells for the deposition of molecular electronic material, wherein a said bank has a face, defining an edge of said well, at an angle to a base of the well of greater than 40 degrees, and wherein said bank is lithographically formed from photoresist.

13. (Withdrawn) A substrate as claimed in claim 12 wherein a height of a said bank above a base of a said well is less than 2 $\mu$ m.

14. (Previously presented) A substrate for a molecular electronic device, the substrate having a plurality of banks defining wells for the deposition of molecular electronic material, wherein a said bank has a face, defining an edge of a said well, at an angle to a base of said well, of greater than 30 degrees, and wherein a height of said bank above a said base of said well is less than 2 $\mu$ m.

15. (Withdrawn) A substrate as claimed in claim 14 wherein said bank is lithographically formed from photoresist.

16. (Withdrawn- currently amended) A substrate as claimed in claimed in claim 12, ~~13 or 15~~ wherein said photoresist comprises a single layer of preferably negative photoresist.

17. (Withdrawn) A substrate as claimed in claim 12 wherein a said bank face angle is greater than 40 degrees.

18. (Withdrawn) A substrate as claimed in claim 12 wherein a said bank face angle is undercut.

19. (Withdrawn) A molecular electronic device including the substrate of claim 12.

20. (Canceled)

Claims 21-32 (Canceled)

33. (Withdrawn) A substrate as claimed in claim 12 wherein a height of a said bank above a base of a said well is less than 1.5  $\mu\text{m}$ .

34. (Withdrawn) A substrate as claimed in claim 14, wherein a height of a said bank above a said base of a said well is less than 1.5 $\mu\text{m}$ .

35. (Withdrawn) A substrate as claimed in claimed in claim 13 wherein said photoresist comprises a single layer of preferably negative photoresist.

36. (Withdrawn) A substrate as claimed in claimed in claim 15 wherein said photoresist comprises a single layer of preferably negative photoresist.

37. (Withdrawn) A substrate as claimed in claim 14 wherein a said bank face angle is greater than 40 degrees.

38. (Withdrawn) A substrate as claimed in claim 14 wherein a said bank face angle is undercut.

39. (Withdrawn) A molecular electronic device including the substrate of claim 14.

40. (Canceled)

41. (Canceled)

42. (Withdrawn) A substrate as claimed in claim 12 wherein said molecular electronic device comprises an organic light emitting diode device.

43. (Withdrawn) A method as claimed in claim 14 wherein said molecular electronic device comprises an organic light emitting diode device.

44. (New) A method as claimed in claim 1 wherein a height of a said bank above a said base of a said well is less than 1.5 $\mu$ m.

45. (New) A method as claimed claim 44 wherein said bank face angle is at least 90 degrees.